Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	EBI/EMI, I²C, IrDA, Memory Card, SPI, SSC, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, WDT
Number of I/O	110
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.75V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3a3128-alur

  - Support for SPI and LIN
  - Optionnal support for IrDA, ISO7816, Hardware Handshaking, RS485 interfaces and Modem Line
- Two Master/Slave Serial Peripheral Interfaces (SPI) with Chip Select Signals
- One Synchronous Serial Protocol Controller
  - Supports I2S and Generic Frame-Based Protocols
- Two Master/Slave Two-Wire Interface (TWI), 400 kbit/s I2C-compatible
- 16-bit Stereo Audio Bitstream
  - Sample Rate Up to 50 KHz
- QTouch® Library Support
  - Capacitive Touch Buttons, Sliders, and Wheels
  - QTouch and QMatrix Acquisition
- On-Chip Debug System (JTAG interface)
  - Nexus Class 2+, Runtime Control, Non-Intrusive Data and Program Trace
- 110 General Purpose Input/Output (GPIOs)
  - Standard or High Speed mode
  - Toggle capability: up to 84 MHz
- Packages
  - 144-ball TFBGA, 11x11 mm, pitch 0.8 mm
  - 144-pin LQFP, 22x22 mm, pitch 0.5 mm
  - 100-ball VFBGA, 7x7 mm, pitch 0.65 mm
- Single 3.3 V Power Supply

Figure 3-2. LQFP144 Pinout

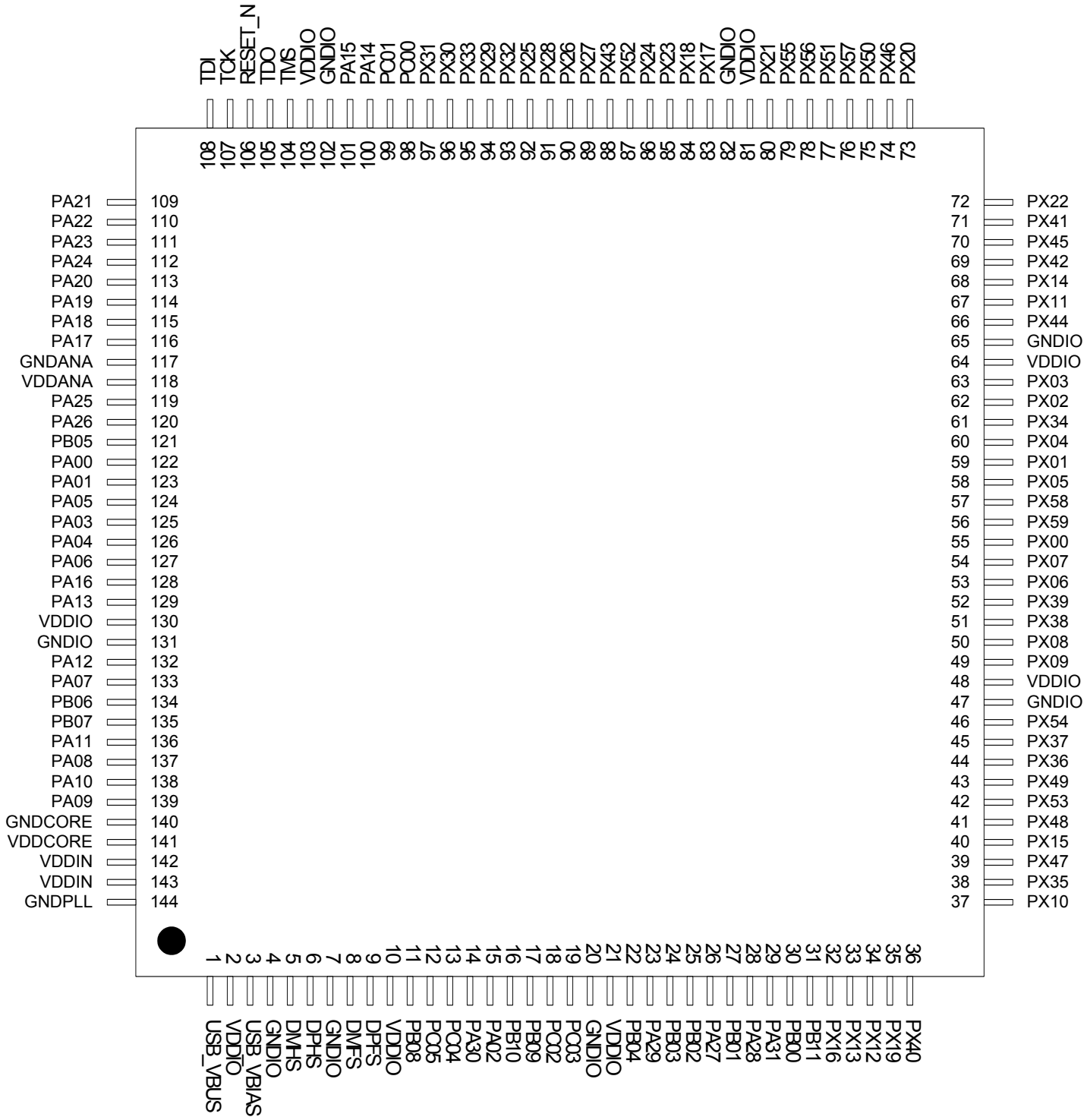
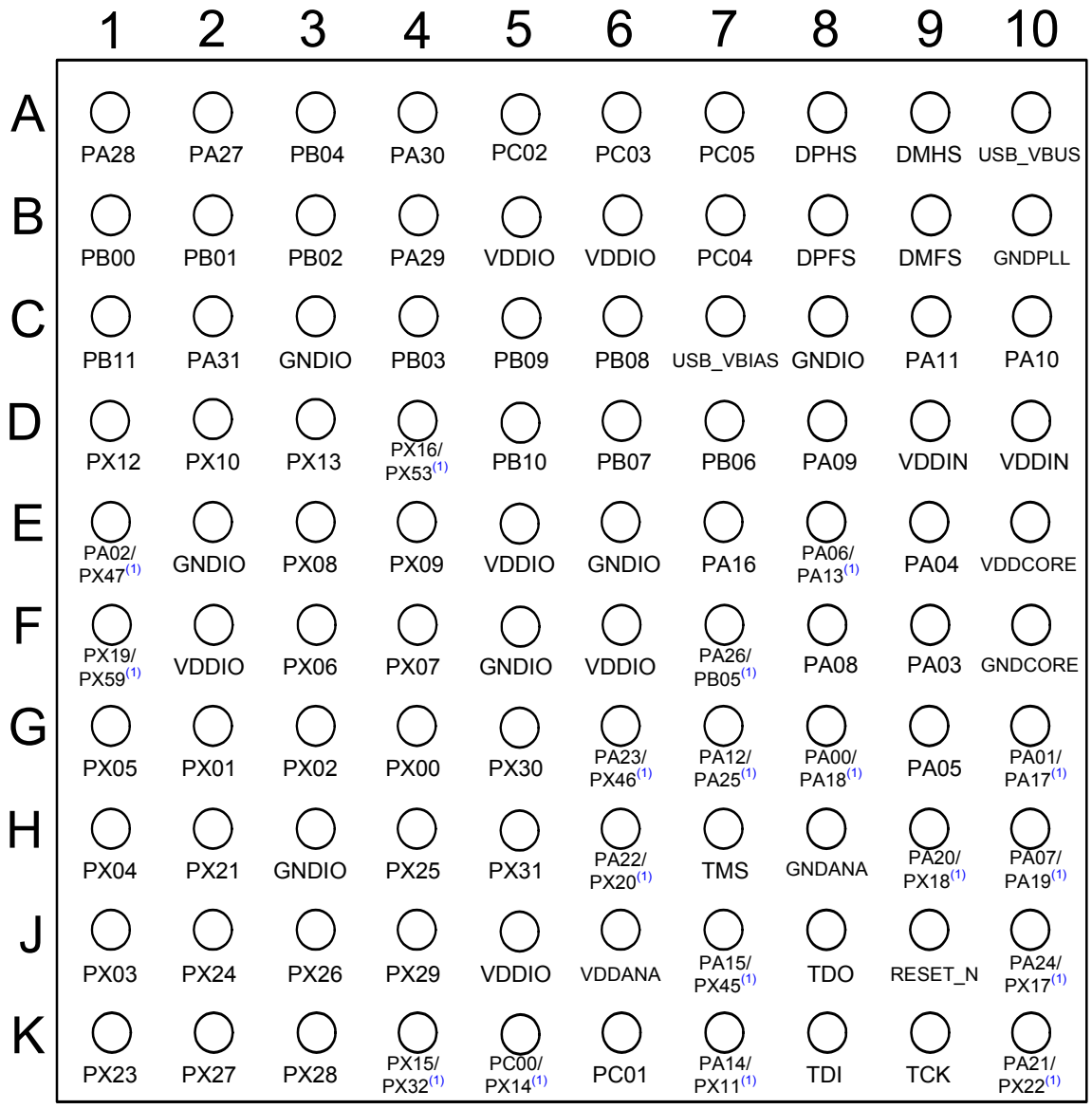


Figure 3-3. VFBGA100 Pinout (top view)



Note: 1. Those balls are physically connected to 2 GPIOs. Software must managed carrefully the GPIO configuration to avoid electrical conflict

Table 3-1. GPIO Controller Function Multiplexing

BGA 144	QFP 144	BGA 100	PIN	GPIO	Supply	PIN Type (2)	GPIO function			
							A	B	C	D
J4	78		PX56	107	VDDIO	x2	EBI - ADDR[21]	EIC - SCAN[2]	USART2 - TXD	
H4	76		PX57	108	VDDIO	x2	EBI - ADDR[20]	EIC - SCAN[1]	USART3 - RXD	
H3	57		PX58	109	VDDIO	x2	EBI - NCS[0]	EIC - SCAN[0]	USART3 - TXD	
G3	56	F1(1)	PX59	110	VDDIO	x2	EBI - NANDWE		MCI - CMD[1]	

Note: 1. Those balls are physically connected to 2 GPIOs. Software must managed carrefully the GPIO configuration to avoid electrical conflict.

2. Refer to "Electrical Characteristics" on page 40 for a description of the electrical properties of the pad types used..

3.2.2 Peripheral Functions

Each GPIO line can be assigned to one of several peripheral functions. The following table describes how the various peripheral functions are selected. The last listed function has priority in case multiple functions are enabled on the same pin.

Table 3-2. Peripheral Functions

Function	Description
GPIO Controller Function multiplexing	GPIO and GPIO peripheral selection A to D
Nexus OCD AUX port connections	OCD trace system
JTAG port connections	JTAG debug port
Oscillators	OSC0, OSC1, OSC32

3.2.3 Oscillator Pinout

The oscillators are not mapped to the normal GPIO functions and their muxings are controlled by registers in the Power Mananger (PM). Please refer to the PM chapter for more information about this.

Table 3-3. Oscillator Pinout

TFBGA144	QFP144	VFBGA100	Pin name	Oscillator pin
A7	18	A5	PC02	XIN0
B7	19	A6	PC03	XOUT0
A8	13	B7	PC04	XIN1
A9	12	A7	PC05	XOUT1
K5	98	K5(1)	PC00	XIN32
H6	99	K6	PC01	XOUT32

Note: 1. This ball is physically connected to 2 GPIOs. Software must managed carrefully the GPIO configuration to avoid electrical conflict

3.3 Signal Descriptions

The following table gives details on signal name classified by peripheral.

Table 3-6. Signal Description List

Signal Name	Function	Type	Active Level	Comments
Power				
VDDIO	I/O Power Supply	Power		3.0 to 3.6V
VDDANA	Analog Power Supply	Power		3.0 to 3.6V
VDDIN	Voltage Regulator Input Supply	Power		3.0 to 3.6V
VDDCORE	Voltage Regulator Output for Digital Supply	Power Output		1.65 to 1.95 V
GNDANA	Analog Ground	Ground		
GNDIO	I/O Ground	Ground		
GNDCORE	Digital Ground	Ground		
GNDPLL	PLL Ground	Ground		
Clocks, Oscillators, and PLL's				
XIN0, XIN1, XIN32	Crystal 0, 1, 32 Input	Analog		
XOUT0, XOUT1, XOUT32	Crystal 0, 1, 32 Output	Analog		
JTAG				
TCK	Test Clock	Input		
TDI	Test Data In	Input		
TDO	Test Data Out	Output		
TMS	Test Mode Select	Input		
Auxiliary Port - AUX				
MCKO	Trace Data Output Clock	Output		
MDO[5:0]	Trace Data Output	Output		
MSEO[1:0]	Trace Frame Control	Output		
EVTI_N	Event In	Input	Low	
EVTO_N	Event Out	Output	Low	
Power Manager - PM				
GCLK[3:0]	Generic Clock Pins	Output		

Table 3-6. Signal Description List

Signal Name	Function	Type	Active Level	Comments
RESET_N	Reset Pin	Input	Low	
DMA Controller - DMACA (optional)				
DMAACK[1:0]	DMA Acknowledge	Output		
DMARQ[1:0]	DMA Requests	Input		
External Interrupt Controller - EIC				
EXTINT[7:0]	External Interrupt Pins	Input		
SCAN[7:0]	Keypad Scan Pins	Output		
NMI	Non-Maskable Interrupt Pin	Input	Low	
General Purpose Input/Output pin - GPIOA, GPIOB, GPIOC, GPIOX				
PA[31:0]	Parallel I/O Controller GPIO port A	I/O		
PB[11:0]	Parallel I/O Controller GPIO port B	I/O		
PC[5:0]	Parallel I/O Controller GPIO port C	I/O		
PX[59:0]	Parallel I/O Controller GPIO port X	I/O		
External Bus Interface - EBI				
ADDR[23:0]	Address Bus	Output		
CAS	Column Signal	Output	Low	
CFCE1	Compact Flash 1 Chip Enable	Output	Low	
CFCE2	Compact Flash 2 Chip Enable	Output	Low	
CFRNW	Compact Flash Read Not Write	Output		
DATA[15:0]	Data Bus	I/O		
NANDOE	NAND Flash Output Enable	Output	Low	
NANDWE	NAND Flash Write Enable	Output	Low	
NCS[5:0]	Chip Select	Output	Low	
NRD	Read Signal	Output	Low	
NWAIT	External Wait Signal	Input	Low	
NWE0	Write Enable 0	Output	Low	
NWE1	Write Enable 1	Output	Low	
RAS	Row Signal	Output	Low	

5. Memories

5.1 Embedded Memories

- **Internal High-Speed Flash**
  - **256KBytes (AT32UC3A3256/S)**
  - **128Kbytes (AT32UC3A3128/S)**
  - **64Kbytes (AT32UC3A364/S)**
    - **0 wait state access at up to 42MHz in worst case conditions**
    - **1 wait state access at up to 84MHz in worst case conditions**
    - **Pipelined Flash architecture, allowing burst reads from sequential Flash locations, hiding penalty of 1 wait state access**
    - **Pipelined Flash architecture typically reduces the cycle penalty of 1 wait state operation to only 15% compared to 0 wait state operation**
    - **100 000 write cycles, 15-year data retention capability**
    - **Sector lock capabilities, Bootloader protection, Security Bit**
    - **32 Fuses, Erased During Chip Erase**
    - **User page for data to be preserved during Chip Erase**
- **Internal High-Speed SRAM**
  - **64KBytes, Single-cycle access at full speed on CPU Local Bus and accessible through the High Speed Bud (HSB) matrix**
  - **2x32KBytes, accessible independently through the High Speed Bud (HSB) matrix**

5.2 Physical Memory Map

The System Bus is implemented as a bus matrix. All system bus addresses are fixed, and they are never remapped in any way, not even in boot.

Note that AVR32 UC CPU uses unsegmented translation, as described in the AVR32UC Technical Architecture Manual.

The 32-bit physical address space is mapped as follows:

Table 5-1. AT32UC3A3A4 Physical Memory Map

Device	Start Address	Size AT32UC3A3256S AT32UC3A3256 AT32UC3A4256S AT32UC3A4256	Size AT32UC3A3128S AT32UC3A3128 AT32UC3A4128S AT32UC3A4128	Size AT32UC3A364S AT32UC3A364 AT32UC3A464S AT32UC3A464
Embedded CPU SRAM	0x00000000	64KByte	64KByte	64KByte
Embedded Flash	0x80000000	256KByte	128KByte	64KByte
EBI SRAM CS0	0xC0000000	16MByte	16MByte	16MByte
EBI SRAM CS2	0xC8000000	16MByte	16MByte	16MByte
EBI SRAM CS3	0xCC000000	16MByte	16MByte	16MByte
EBI SRAM CS4	0xD8000000	16MByte	16MByte	16MByte
EBI SRAM CS5	0xDC000000	16MByte	16MByte	16MByte
EBI SRAM CS1 /SDRAM CS0	0xD0000000	128MByte	128MByte	128MByte
USB Data	0xE0000000	64KByte	64KByte	64KByte

Table 5-2. Peripheral Address Mapping

0xFFFF0C00	PM	Power Manager - PM
0xFFFF0D00	RTC	Real Time Counter - RTC
0xFFFF0D30	WDT	Watchdog Timer - WDT
0xFFFF0D80	EIC	External Interrupt Controller - EIC
0xFFFF1000	GPIO	General Purpose Input/Output Controller - GPIO
0xFFFF1400	USART0	Universal Synchronous/Asynchronous Receiver/Transmitter - USART0
0xFFFF1800	USART1	Universal Synchronous/Asynchronous Receiver/Transmitter - USART1
0xFFFF1C00	USART2	Universal Synchronous/Asynchronous Receiver/Transmitter - USART2
0xFFFF2000	USART3	Universal Synchronous/Asynchronous Receiver/Transmitter - USART3
0xFFFF2400	SPI0	Serial Peripheral Interface - SPI0
0xFFFF2800	SPI1	Serial Peripheral Interface - SPI1
0xFFFF2C00	TWIM0	Two-wire Master Interface - TWIM0
0xFFFF3000	TWIM1	Two-wire Master Interface - TWIM1
0xFFFF3400	SSC	Synchronous Serial Controller - SSC
0xFFFF3800	TC0	Timer/Counter - TC0
0xFFFF3C00	ADC	Analog to Digital Converter - ADC
0xFFFF4000	ABDAC	Audio Bitstream DAC - ABDAC
0xFFFF4400	TC1	Timer/Counter - TC1

Table 5-2. Peripheral Address Mapping

0xFFFF5000	TWIS0	Two-wire Slave Interface - TWIS0
0xFFFF5400	TWIS1	Two-wire Slave Interface - TWIS1

5.4 CPU Local Bus Mapping

Some of the registers in the GPIO module are mapped onto the CPU local bus, in addition to being mapped on the Peripheral Bus. These registers can therefore be reached both by accesses on the Peripheral Bus, and by accesses on the local bus.

Mapping these registers on the local bus allows cycle-deterministic toggling of GPIO pins since the CPU and GPIO are the only modules connected to this bus. Also, since the local bus runs at CPU speed, one write or read operation can be performed per clock cycle to the local bus-mapped GPIO registers.

The following GPIO registers are mapped on the local bus:

Table 5-3. Local Bus Mapped GPIO Registers

Port	Register	Mode	Local Bus Address	Access
0	Output Driver Enable Register (ODER)	WRITE	0x40000040	Write-only
		SET	0x40000044	Write-only
		CLEAR	0x40000048	Write-only
		TOGGLE	0x4000004C	Write-only
	Output Value Register (OVR)	WRITE	0x40000050	Write-only
		SET	0x40000054	Write-only
		CLEAR	0x40000058	Write-only
		TOGGLE	0x4000005C	Write-only
	Pin Value Register (PVR)	-	0x40000060	Read-only
1	Output Driver Enable Register (ODER)	WRITE	0x40000140	Write-only
		SET	0x40000144	Write-only
		CLEAR	0x40000148	Write-only
		TOGGLE	0x4000014C	Write-only
	Output Value Register (OVR)	WRITE	0x40000150	Write-only
		SET	0x40000154	Write-only
		CLEAR	0x40000158	Write-only
		TOGGLE	0x4000015C	Write-only
	Pin Value Register (PVR)	-	0x40000160	Read-only

7. Electrical Characteristics

7.1 Absolute Maximum Ratings*

Operating Temperature	-40°C to +85°C
Storage Temperature	-60°C to +150°C
Voltage on Input Pin with respect to Ground	-0.3V to 3.6V
Maximum Operating Voltage (VDDCORE)	1.95V
Maximum Operating Voltage (VDDIO)	3.6V
Total DC Output Current on all I/O Pin	
for TQFP144 package	370 mA
for TFBGA144 package	370 mA

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

7.2.1 I/O Pin Output Level Typical Characteristics

Figure 7-1. I/O Pin drive x2 Output Low Level Voltage (VOL) vs. Source Current

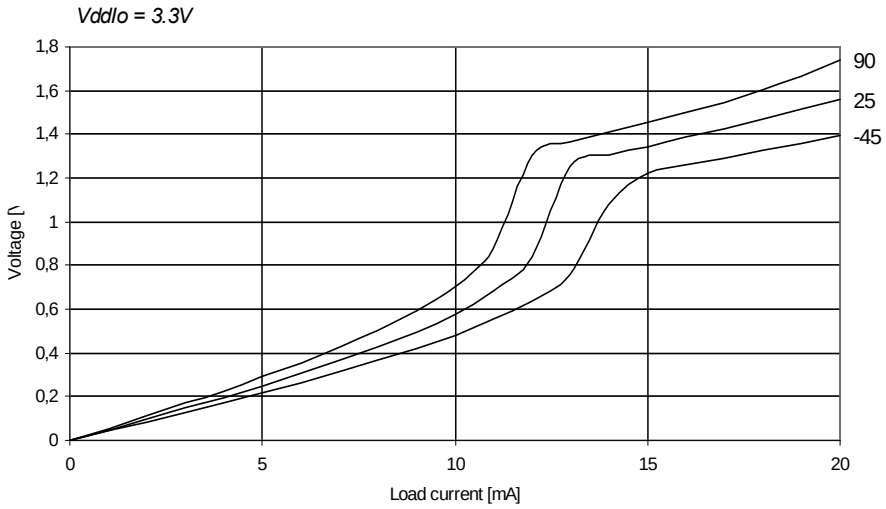
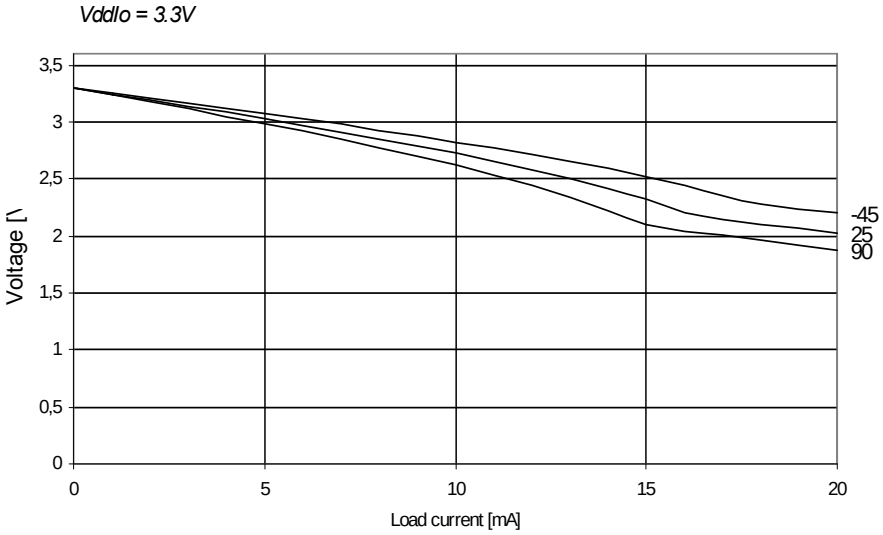


Figure 7-2. I/O Pin drive x2 Output High Level Voltage (VOH) vs. Source Current



7.3 I/O pin Characteristics

These parameters are given in the following conditions:

- V_{DDCORE} = 1.8V
- V_{DDIO} = 3.3V
- Ambient Temperature = 25°C

Table 7-13. Typical Cuurent Consumption by Peripheral

Peripheral	Typ.	Unit
ADC	7	µA/MHz
AES	80	
ABDAC	10	
DMACA	70	
EBI	23	
EIC	0.5	
GPIO	37	
INTC	3	
MCI	40	
MSI	10	
PDCA	20	
SDRAM	5	
SMC	9	
SPI	6	
SSC	10	
RTC	5	
TC	8	
TWIM	2	
TWIS	2	
USART	10	
USBB	90	
WDT	2	

7.7 System Clock Characteristics

These parameters are given in the following conditions:

- V_{DDCORE} = 1.8V

7.7.1 CPU/HSB Clock Characteristics

Table 7-14. Core Clock Waveform Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPCPU})$	CPU Clock Frequency	-40°C < Ambient Temperature < 70°C			84	MHz
$1/(t_{CPCPU})$	CPU Clock Frequency	-40°C < Ambient Temperature < 85°C			66	MHz

7.7.2 PBA Clock Characteristics

Table 7-15. PBA Clock Waveform Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPPBA})$	PBA Clock Frequency	-40°C < Ambient Temperature < 70°C			84	MHz
$1/(t_{CPPBA})$	PBA Clock Frequency	-40°C < Ambient Temperature < 85°C			66	MHz

7.7.3 PBB Clock Characteristics

Table 7-16. PBB Clock Waveform Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CPPBB})$	PBB Clock Frequency	-40°C < Ambient Temperature < 70°C			84	MHz
$1/(t_{CPPBB})$	PBB Clock Frequency	-40°C < Ambient Temperature < 85°C			66	MHz

Table 7-32. SMC Read Signals with no Hold Settings

Symbol	Parameter	Min.	Unit
NRD Controlled (READ_MODE = 1)			
SMC_{19}	Data Setup before NRD High	13.7	ns
SMC_{20}	Data Hold after NRD High	1	ns
NRD Controlled (READ_MODE = 0)			
SMC_{21}	Data Setup before NCS High	13.3	ns
SMC_{22}	Data Hold after NCS High	0	ns

Table 7-33. SMC Write Signals with Hold Settings

Symbol	Parameter	Min.	Unit
NRD Controlled (READ_MODE = 1)			
SMC_{23}	Data Out Valid before NWE High	(nwe pulse length - 1) * t_{CPSMC} - 0.9	ns
SMC_{24}	Data Out Valid after NWE High(1)	nwe hold length * t_{CPSMC} - 6	ns
SMC_{25}	NWE High to NBS0/A0 Change(1)	nwe hold length * t_{CPSMC} - 1.9	ns
SMC_{26}	NWE High to NBS1 Change(1)	nwe hold length * t_{CPSMC} - 1.9	ns
SMC_{29}	NWE High to A1 Change(1)	nwe hold length * t_{CPSMC} - 1.9	ns
SMC_{31}	NWE High to A2 - A23 Change(1)	nwe hold length * t_{CPSMC} - 1.7	ns
SMC_{32}	NWE High to NCS Inactive(1)	(nwe hold length - ncs wr hold length)* t_{CPSMC} - 2.9	ns
SMC_{33}	NWE Pulse Width	nwe pulse length * t_{CPSMC} - 0.9	ns
NRD Controlled (READ_MODE = 0)			
SMC_{34}	Data Out Valid before NCS High	(ncs wr pulse length - 1)* t_{CPSMC} - 4.6	ns
SMC_{35}	Data Out Valid after NCS High(1)	ncs wr hold length * t_{CPSMC} - 5.8	ns
SMC_{36}	NCS High to NWE Inactive(1)	(ncs wr hold length - nwe hold length)* t_{CPSMC} - 0.6	ns

Note: 1. hold length = total cycle duration - setup duration - pulse duration. “hold length” is for “ncs wr hold length” or “nwe hold length"

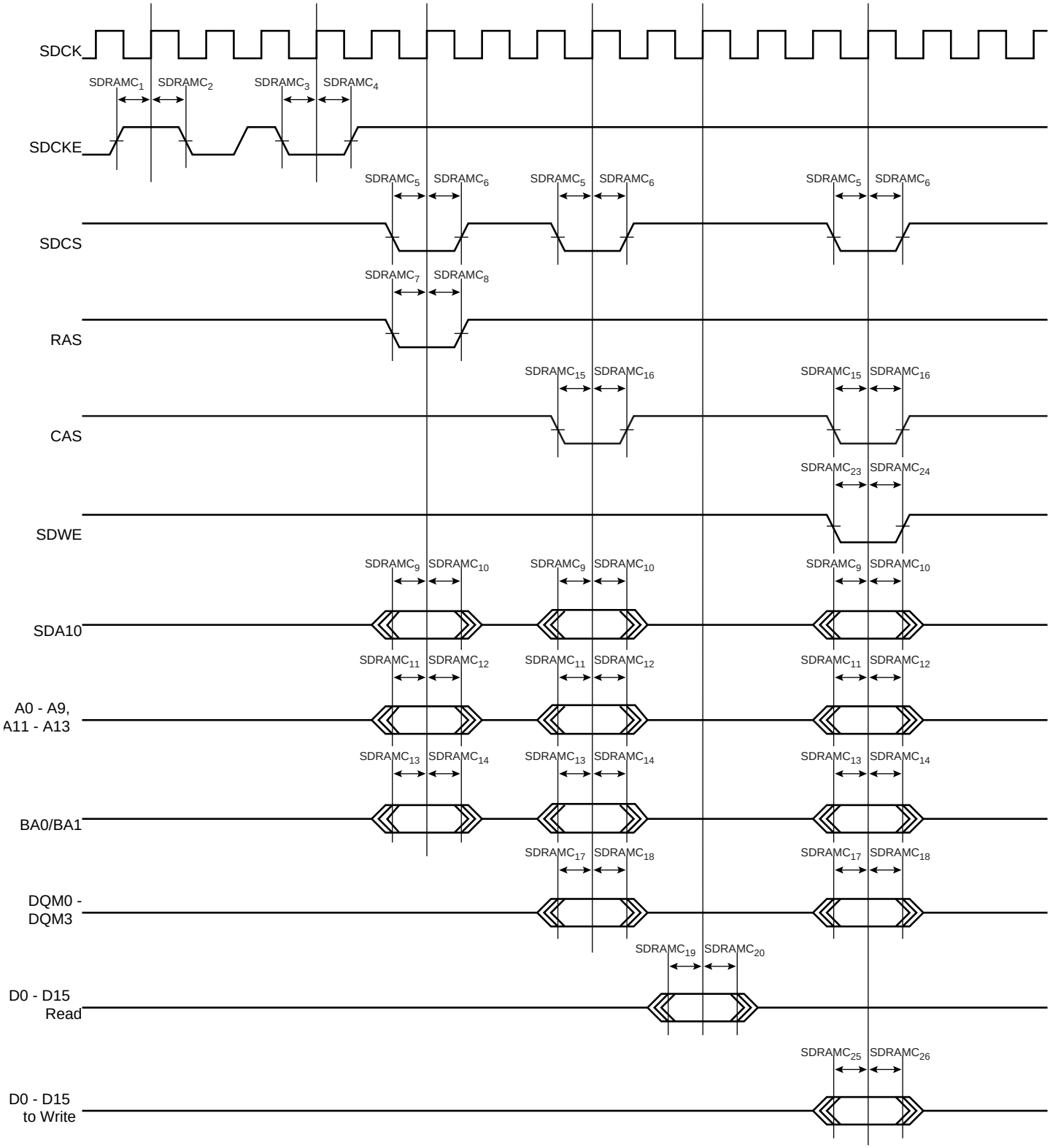
Table 7-34. SMC Write Signals with No Hold Settings (NWE Controlled only)

Symbol	Parameter	Min.	Unit
SMC_{37}	NWE Rising to A2-A25 Valid	5.4	ns
SMC_{38}	NWE Rising to NBS0/A0 Valid	5	ns
SMC_{39}	NWE Rising to NBS1 Change	5	ns
SMC_{40}	NWE Rising to A1/NBS2 Change	5	ns
SMC_{41}	NWE Rising to NBS3 Change	5	ns
SMC_{42}	NWE Rising to NCS Rising	5.1	ns

Table 7-36. SDRAM Clock Signal

Symbol	Parameter	Conditions	Min.	Max.	Unit
$SDRAMC_{13}$	Bank Change before SDCK Rising Edge		6.3		ns
$SDRAMC_{14}$	Bank Change after SDCK Rising Edge		2.4		ns
$SDRAMC_{15}$	CAS Low before SDCK Rising Edge		7.4		ns
$SDRAMC_{16}$	CAS High after SDCK Rising Edge		1.9		ns
$SDRAMC_{17}$	DQM Change before SDCK Rising Edge		6.4		ns
$SDRAMC_{18}$	DQM Change after SDCK Rising Edge		2.2		ns
$SDRAMC_{19}$	D0-D15 in Setup before SDCK Rising Edge		9		ns
$SDRAMC_{20}$	D0-D15 in Hold after SDCK Rising Edge		0		ns
$SDRAMC_{23}$	SDWE Low before SDCK Rising Edge		7.6		ns
$SDRAMC_{24}$	SDWE High after SDCK Rising Edge		1.8		ns
$SDRAMC_{25}$	D0-D15 Out Valid before SDCK Rising Edge		7.1		ns
$SDRAMC_{26}$	D0-D15 Out Valid after SDCK Rising Edge		1.5		ns

Figure 7-9. SDRAMC Signals relative to SDCK.



TWIS stretch on Address match error
When the TWIS stretches TWCK due to a slave address match, it also holds TWD low for the same duration if it is to be receiving data. When TWIS releases TWCK, it releases TWD at the same time. This can cause a TWI timing violation.
Fix/Workaround
None.

10.1.14 SSC

Frame Synchro and Frame Synchro Data are delayed by one clock cycle
The frame synchro and the frame synchro data are delayed from 1 SSC_CLOCK when:
- Clock is CKDIV
- The START is selected on either a frame synchro edge or a level
- Frame synchro data is enabled
- Transmit clock is gated on output (through CKO field)

Fix/Workaround
Transmit or receive CLOCK must not be gated (by the mean of CKO field) when START condition is performed on a generated frame synchro.

10.1.15 FLASHC

Corrupted read in flash may happen after fuses write or erase operations (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands)
After a flash fuse write or erase operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands), reading (data read or code fetch) in flash may fail. This may lead to an exception or to other errors derived from this corrupted read access.
Fix/Workaround
Before the flash fuse write or erase operation, enable the flash high speed mode (FLASHC HSEN command). The flash fuse write or erase operations (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands) must be issued from RAM or through the EBI. After these commands, read 3 times one flash page initialized to 00h. Disable the flash high speed mode (FLASHC HSDIS command). It is then possible to safely read or code fetch the flash.

10.2 Rev. E

10.2.1 General

Devices cannot operate with CPU frequency higher than 66MHz in 1WS and 36MHz in 0WS
Fix/Workaround
None

Increased Power Consumption in VDDIO in sleep modes
If the OSC0 is enabled in crystal mode when entering a sleep mode where the OSC0 is disabled, this will lead to an increased power consumption in VDDIO.
Fix/Workaround
Disable the OSC0 through the System Control Interface (SCIF) before going to any sleep mode where the OSC0 is disabled, or pull down or up XIN0 and XOUT0 with 1 Mohm resistor.

Power consumption in static mode The power consumption in static mode can be up to 330µA on some parts (typical at 25°C)

SMBALERT bit may be set after reset
The SMBus Alert (SMBALERT) bit in the Status Register (SR) might be erroneously set after system reset.
Fix/Workaround
After system reset, clear the SR.SMBALERT bit before commencing any TWI transfer.

10.2.13 TWIS

Clearing the NAK bit before the BTF bit is set locks up the TWI bus
When the TWIS is in transmit mode, clearing the NAK Received (NAK) bit of the Status Register (SR) before the end of the Acknowledge/Not Acknowledge cycle will cause the TWIS to attempt to continue transmitting data, thus locking up the bus.
Fix/Workaround
Clear SR.NAK only after the Byte Transfer Finished (BTF) bit of the same register has been set.

TWIS stretch on Address match error
When the TWIS stretches TWCK due to a slave address match, it also holds TWD low for the same duration if it is to be receiving data. When TWIS releases TWCK, it releases TWD at the same time. This can cause a TWI timing violation.
Fix/Workaround
None.

10.2.14 MCI

MCI_CLK features is not available on PX12, PX13 and PX40
Fix/Workaround
MCI_CLK feature is available on PA27 only.

The busy signal of the responses R1b is not taken in account for CMD12 STOP_TRANSFER
It is not possible to know the busy status of the card during the response (R1b) for the commands CMD12.
Fix/Workaround
The card busy line should be polled through the GPIO Input Value register (IVR) for commands CMD12.

10.2.15 SSC

Frame Synchro and Frame Synchro Data are delayed by one clock cycle
The frame synchro and the frame synchro data are delayed from 1 SSC_CLOCK when:
- Clock is CKDIV
- The START is selected on either a frame synchro edge or a level
- Frame synchro data is enabled
- Transmit clock is gated on output (through CKO field)

Fix/Workaround
Transmit or receive CLOCK must not be gated (by the mean of CKO field) when START condition is performed on a generated frame synchro.

10.3.9 PDCA

PCONTROL.CHxRES is non-functional
PCONTROL.CHxRES is non-functional. Counters are reset at power-on, and cannot be reset by software.
Fix/Workaround
Software needs to keep history of performance counters.

Transfer error will stall a transmit peripheral handshake interface
If a transfer error is encountered on a channel transmitting to a peripheral, the peripheral handshake of the active channel will stall and the PDCA will not do any more transfers on the affected peripheral handshake interface.
Fix/Workaround
Disable and then enable the peripheral after the transfer error.

10.3.10 AES

URAD (Unspecified Register Access Detection Status) does not detect read accesses to the write-only KEYW[5..8]R registers
Fix/Workaround
None.

10.3.11 HMATRIX

In the PRAS and PRBS registers, the MxPR fields are only two bits
In the PRAS and PRBS registers, the MxPR fields are only two bits wide, instead of four bits. The unused bits are undefined when reading the registers.
Fix/Workaround
Mask undefined bits when reading PRAS and PRBS.

10.3.12 TWIM

TWIM SR.IDLE goes high immediately when NAK is received
When a NAK is received and there is a non-zero number of bytes to be transmitted, SR.IDLE goes high immediately and does not wait for the STOP condition to be sent. This does not cause any problem just by itself, but can cause a problem if software waits for SR.IDLE to go high and then immediately disables the TWIM by writing a one to CR.MDIS. Disabling the TWIM causes the TWCK and TWD pins to go high immediately, so the STOP condition will not be transmitted correctly.
Fix/Workaround
If possible, do not disable the TWIM. If it is absolutely necessary to disable the TWIM, there must be a software delay of at least two TWCK periods between the detection of SR.IDLE==1 and the disabling of the TWIM.

TWIM TWALM polarity is wrong
The TWALM signal in the TWIM is active high instead of active low.
Fix/Workaround
Use an external inverter to invert the signal going into the TWIM. When using both TWIM and TWIS on the same pins, the TWALM cannot be used.

10.3.13 TWIS

TWIS Version Register reads zero
TWIS Version Register (VR) reads zero instead of 0x112.

7.10 USB Transceiver Characteristics 55
7.11 EBI Timings 57
7.12 JTAG Characteristics 63
7.13 SPI Characteristics 64
7.14 MCI 66
7.15 Flash Memory Characteristics 67

8 Mechanical Characteristics 68

8.1 Thermal Considerations 68
8.2 Package Drawings 69
8.3 Soldering Profile 72

9 Ordering Information 73

10 Errata 74

10.1 Rev. H 74
10.2 Rev. E 78
10.3 Rev. D 84

11 Datasheet Revision History 90

11.1 Rev. H– 10/12 90
11.2 Rev. G– 11/11 90
11.3 Rev. F – 08/11 90
11.4 Rev. E – 06/11 90
11.5 Rev. D – 04/11 90
11.6 Rev. C – 03/10 90
11.7 Rev. B – 08/09 91
11.8 Rev. A – 03/09 91